## **SECTION 1 - SERVICING**

#### 1. Preventive Maintenance Procedures

Contains routine maintenance instructions for cleaning and inspecting the Test Set.

CAUTION: DISCONNECT POWER FROM TEST SET TO AVOID POSSIBLE DAMAGE TO ELECTRONIC CIRCUITS.

#### A. External Cleaning

STEP PROCEDURE

- 1. Clean front panel and display face with soft lint-free cloth. If dirt is difficult to remove, dampen cloth with water and mild liquid detergent.
- 2. Remove grease, fungus and ground-in dirt from surfaces with soft lint-free cloth dampened (not soaked) with isopropyl alcohol.
- 3. Remove dust and dirt from connectors with soft-bristled brush.
- Cover connectors, not in use, with suitable dust cover to prevent tarnishing of connector contacts.
- 5. Clean cables with soft lint-free cloth.
- 6. Paint exposed metal surface to avoid corrosion.

### B. Internal Cleaning



THIS EQUIPMENT CONTAINS PARTS
SENSITIVE TO DAMAGE
BY ELECTROSTATIC DISCHARGE (ESD)

CAUTION: DO NOT MOVE COMPONENTS ON CIRCUIT BOARDS OR DISASSEMBLE

CONNECTORS NEEDLESSLY TO AVOID POSSIBLE DAMAGE.

CAUTION: DO NOT OPEN COMPLEX INTERNAL MODULES FOR THE SOLE PURPOSE

OF CLEANING AND INSPECTION.

Remove dust with hand-controlled dry air jet of 15 psi (1.054 kg/cm<sup>2</sup>) and wipe internal chassis parts and frame with soft lint-free cloth moistened with isopropyl alcohol.

# ROFLEX MAINTENANCE MANUAL TCAS-201-2

### C. Visual Inspection

## STEP

- 1. Inspect Chassis for:
  - Tightness of sub-assemblies and chassis mounted connectors.

**PROCEDURE** 

- Corrosion or damage to metal surfaces.
- 2. Inspect Capacitors for:
  - Loose mounting, deformities or obvious physical damage.
  - Leakage or corrosion around leads.
- 3. Inspect Connectors for:
  - Loose or broken parts, cracked insulation and bad contacts.
- 4. Inspect Circuit Boards for:
  - Corrosion or damage to connectors.
  - Damage to mounted components including crystals and ICs.
  - Freedom from foreign material.
- 5. Inspect Resistors for:
  - Cracked, broken, charred or blistered bodies.
  - Loose or corroded soldering connections.
- 6. Inspect Semiconductors for:
  - Cracked, broken, charred or discolored bodies.
  - Correct placement and condition of seals around leads.
- 7. Inspect Wiring for:
  - Broken or loose ends and connections.
  - Proper dress relative to other chassis parts.

NOTE: Verify wrapped wiring is tight.